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FIG. 1A

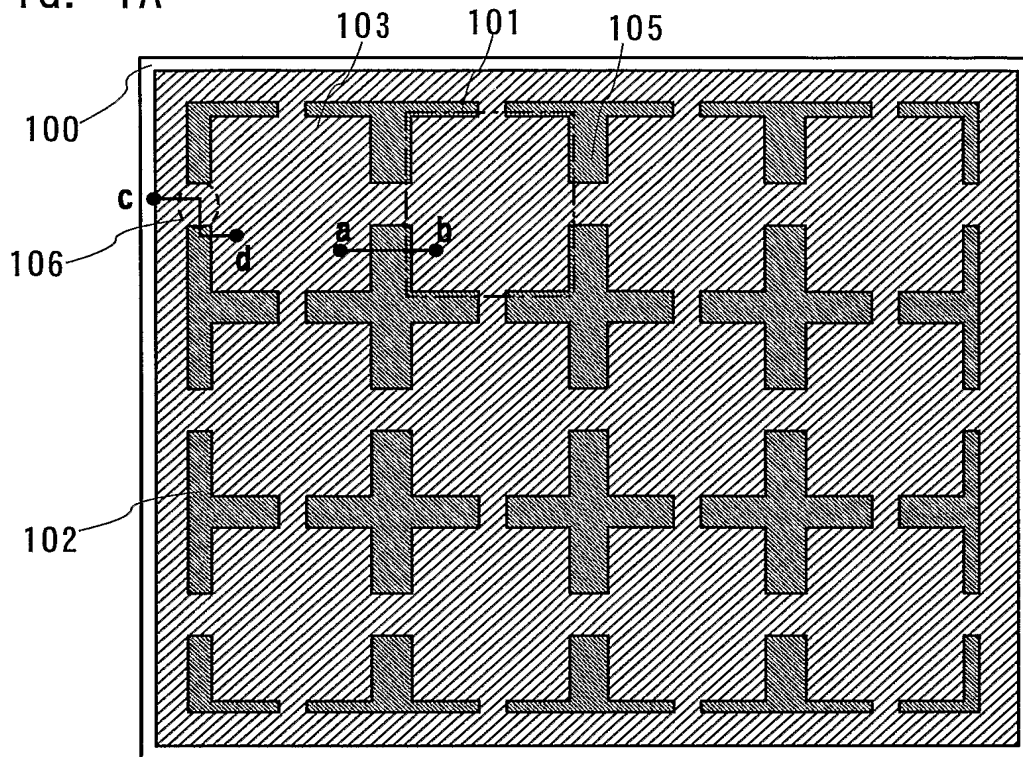


FIG. 1B

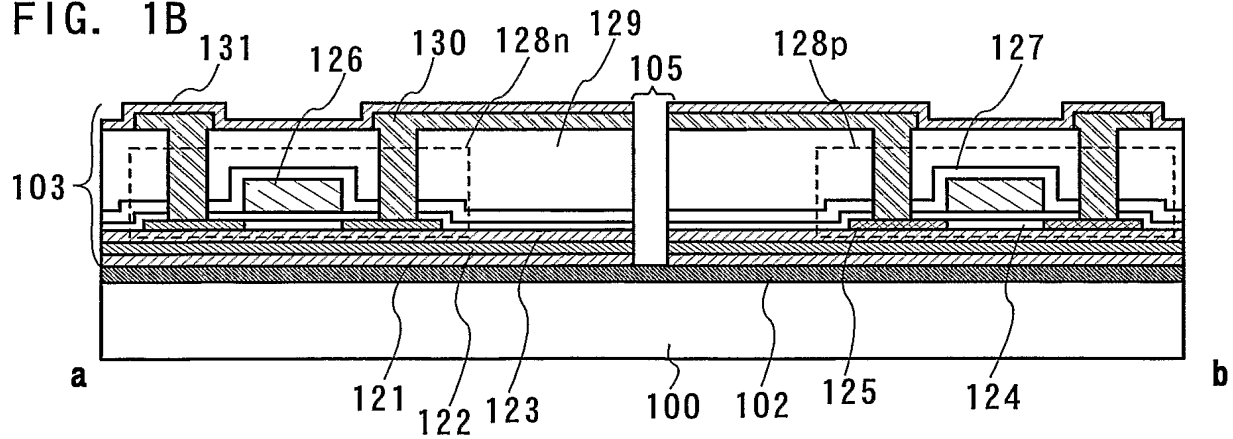
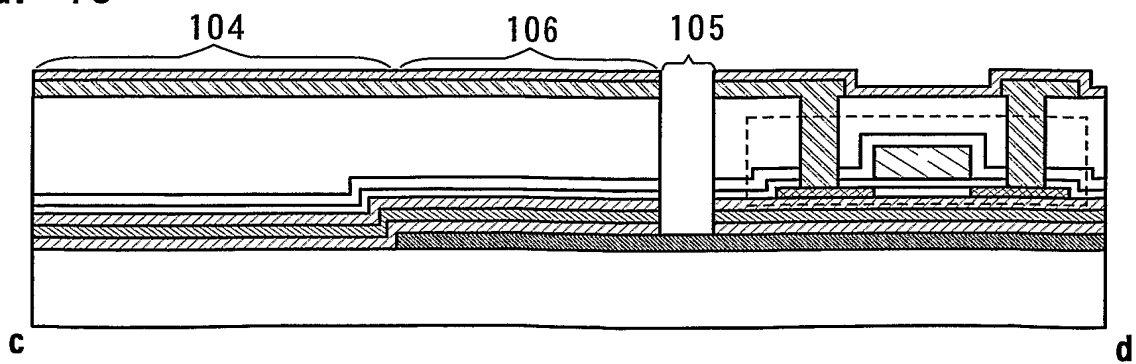


FIG. 1C



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FIG. 2A

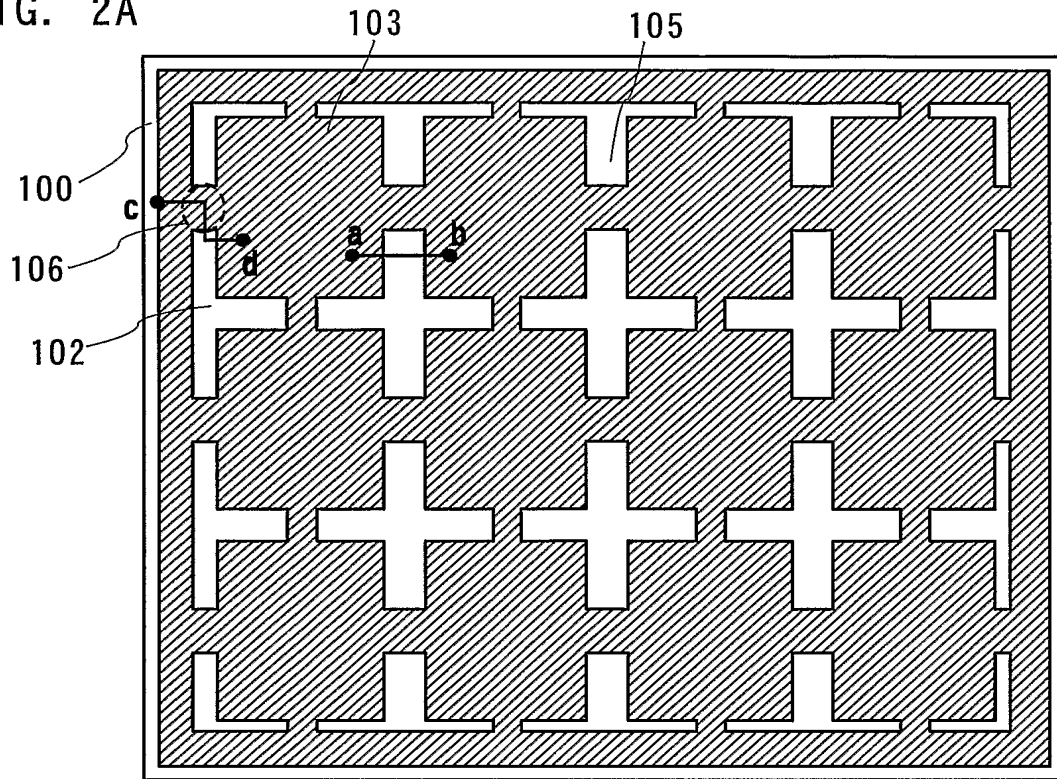


FIG. 2B

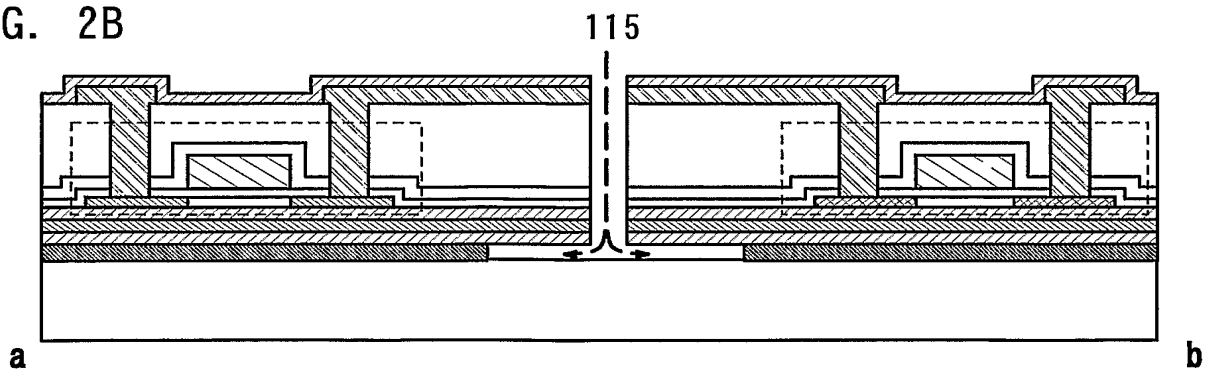


FIG. 2C

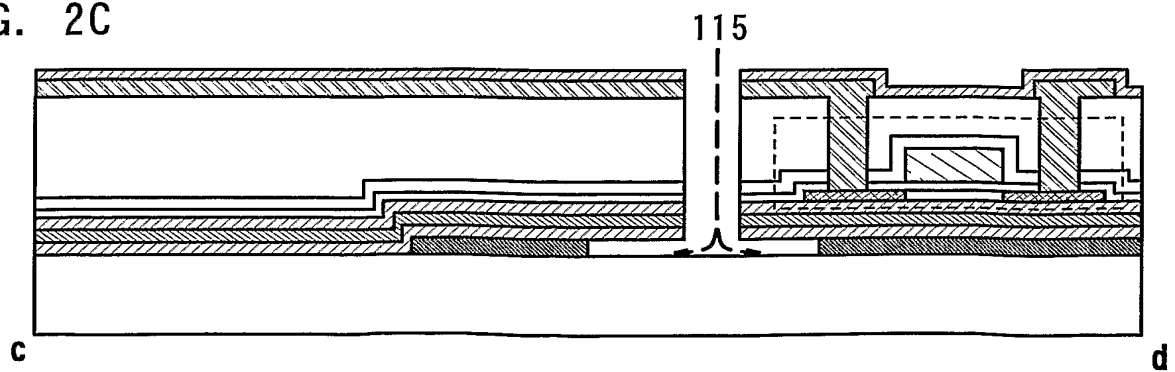


FIG. 3A

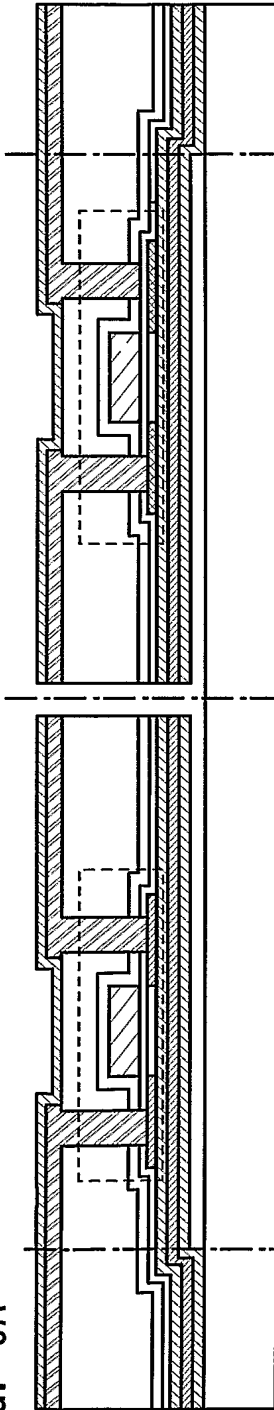


FIG. 3B

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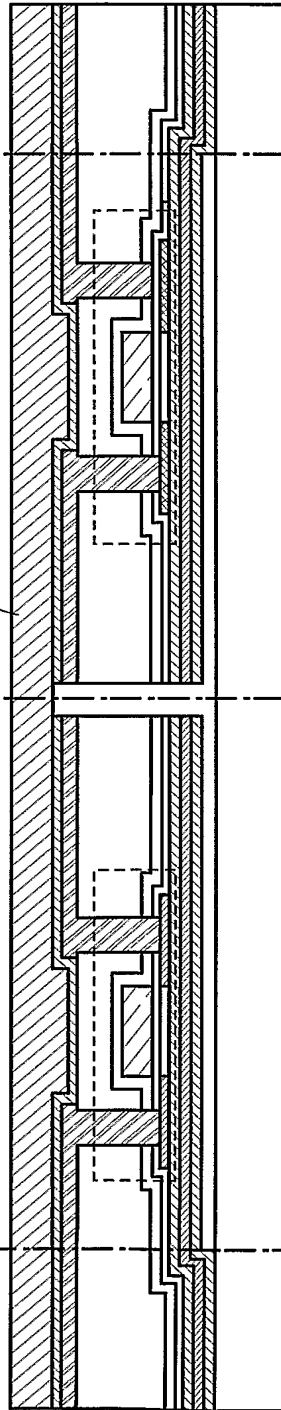


FIG. 3C

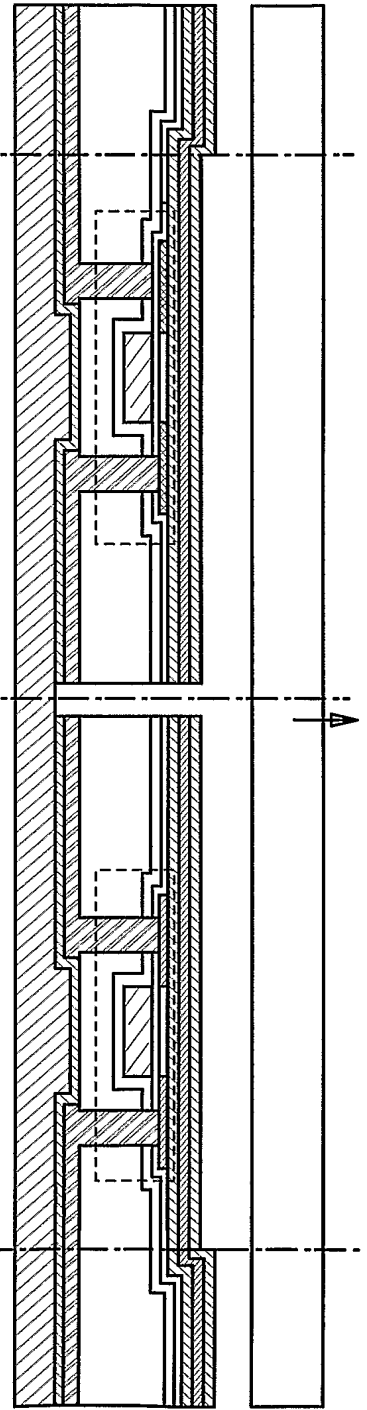


FIG. 4A

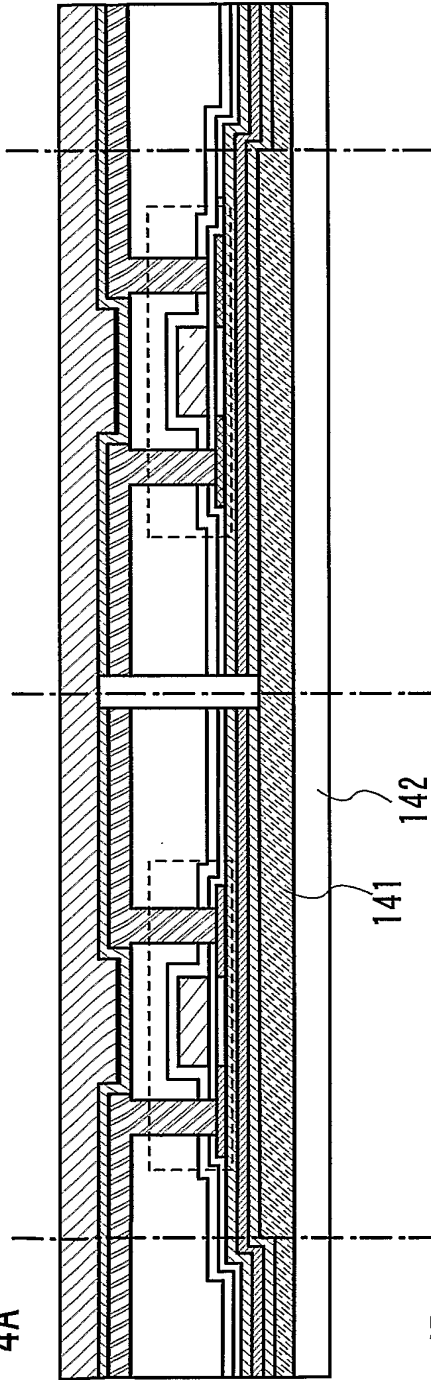


FIG. 4B

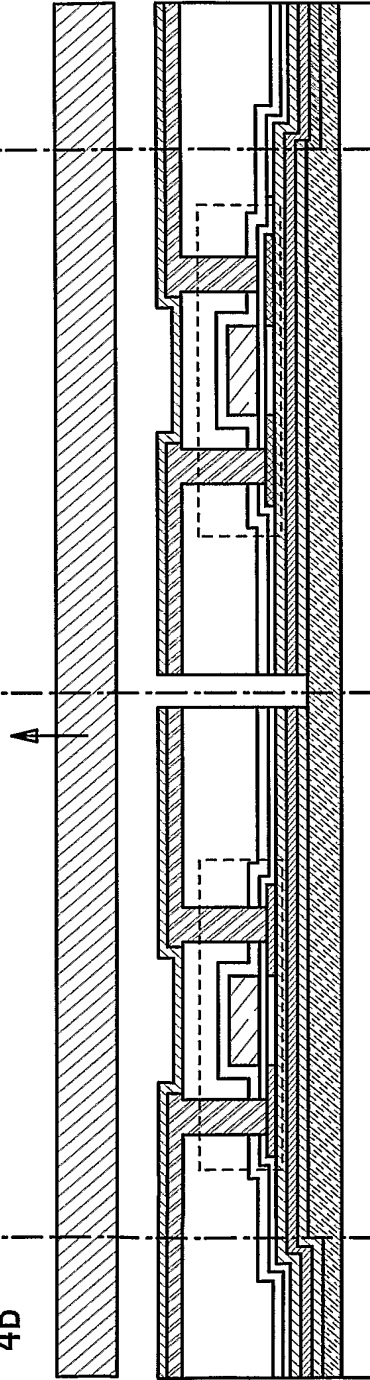
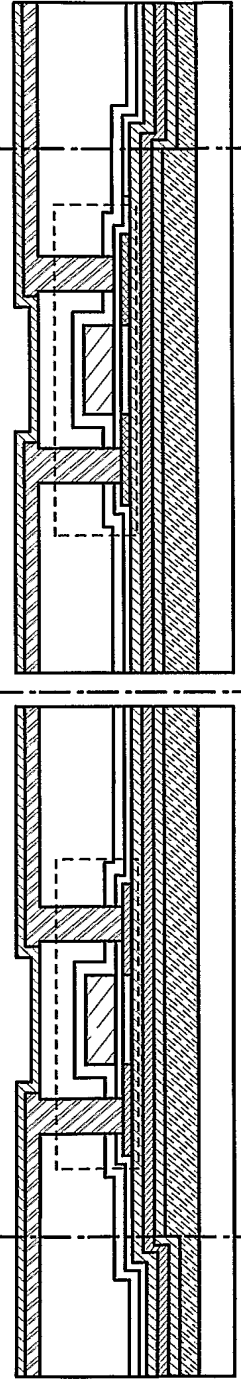
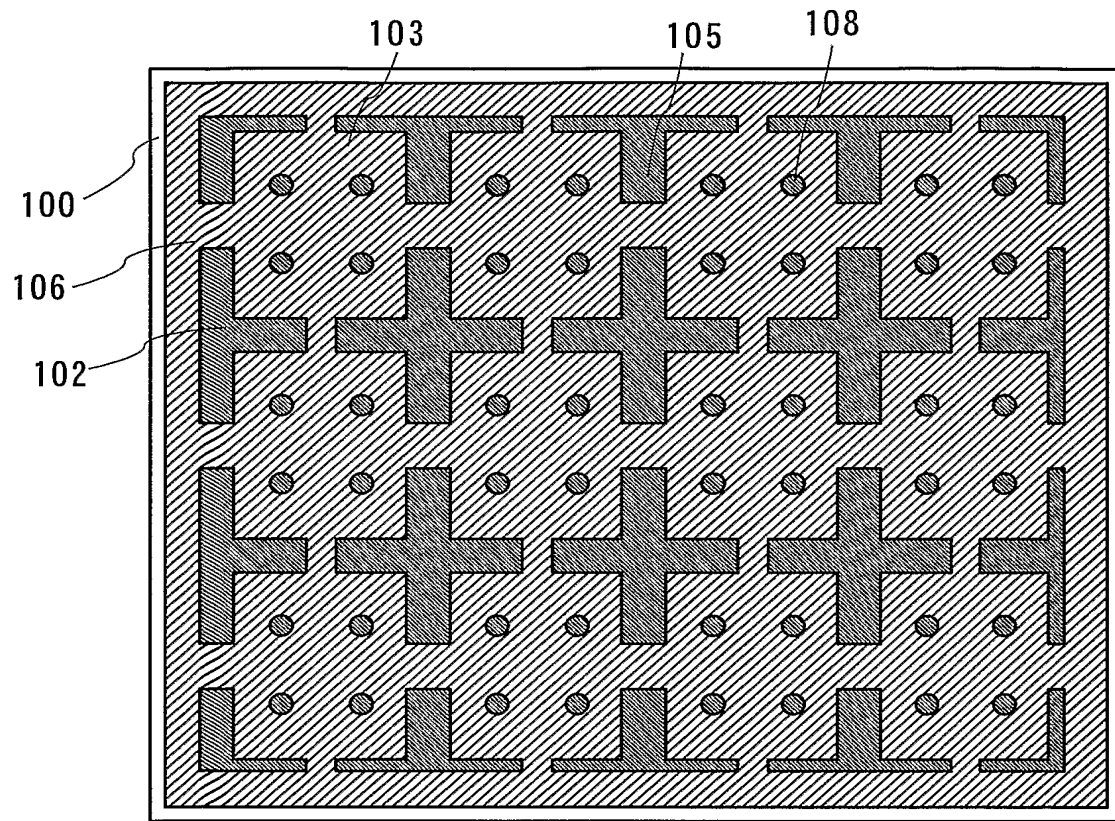


FIG. 4C



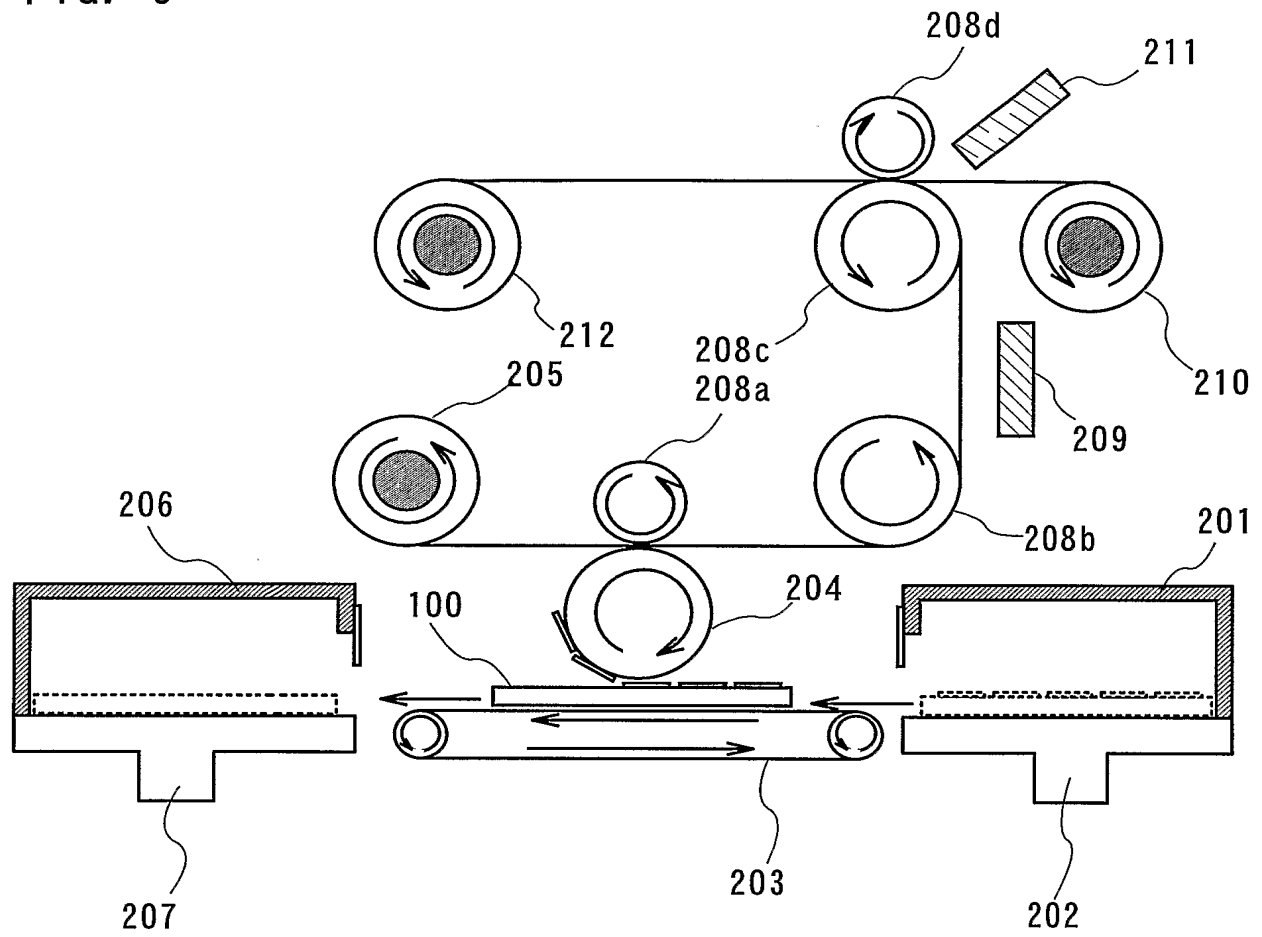
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FIG. 5



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FIG. 6



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FIG. 7A

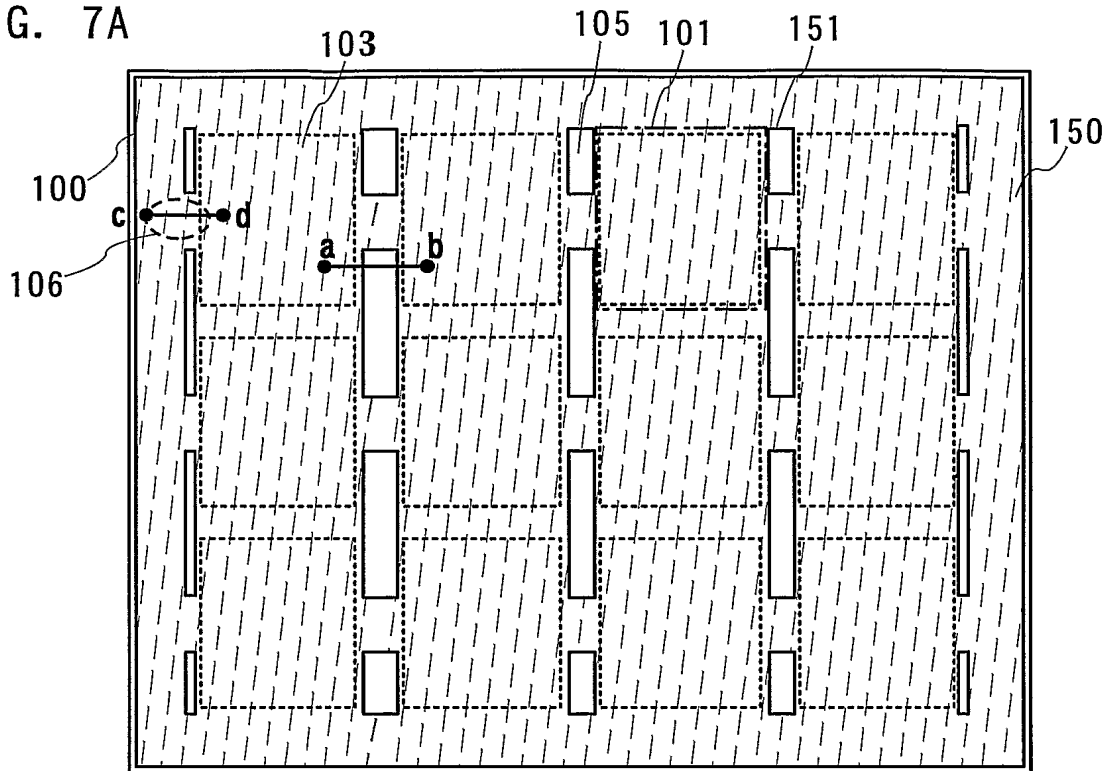


FIG. 7B

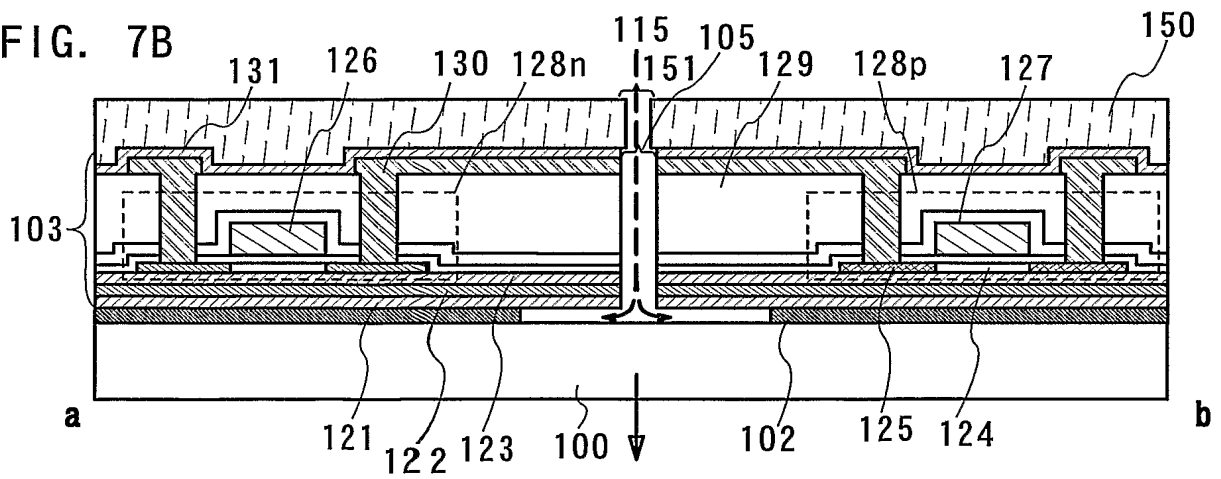


FIG. 7C

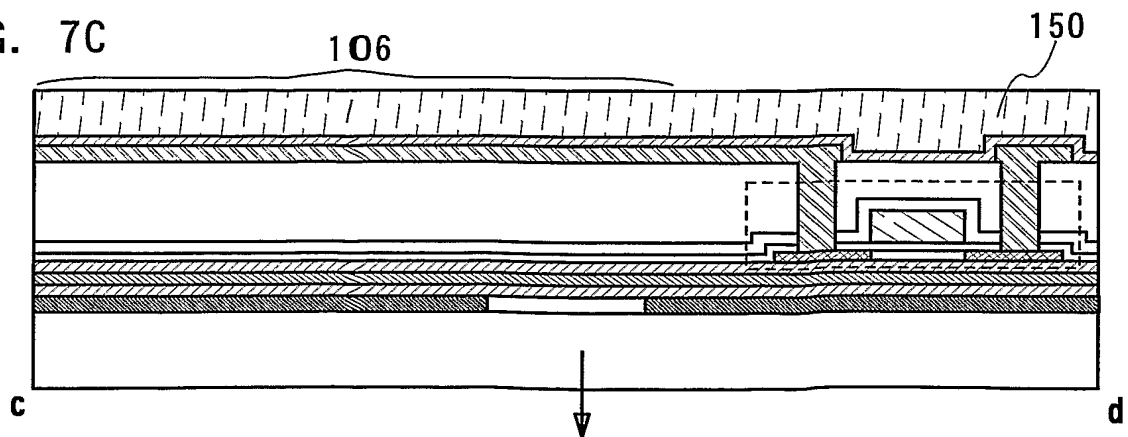


FIG. 8A

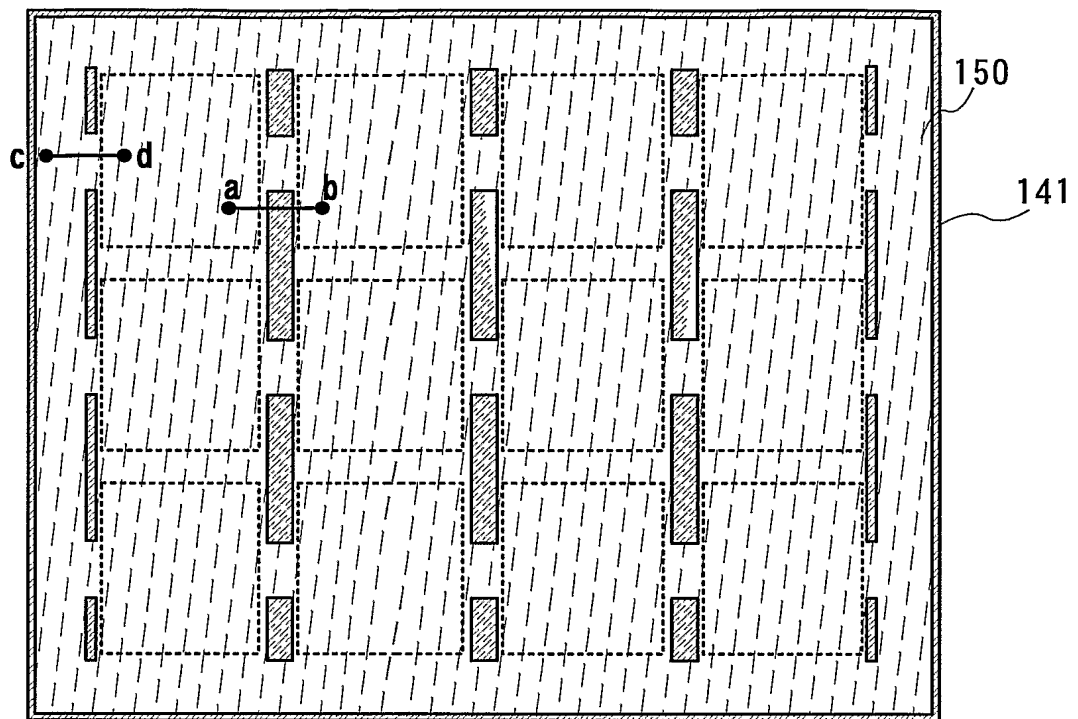


FIG. 8B

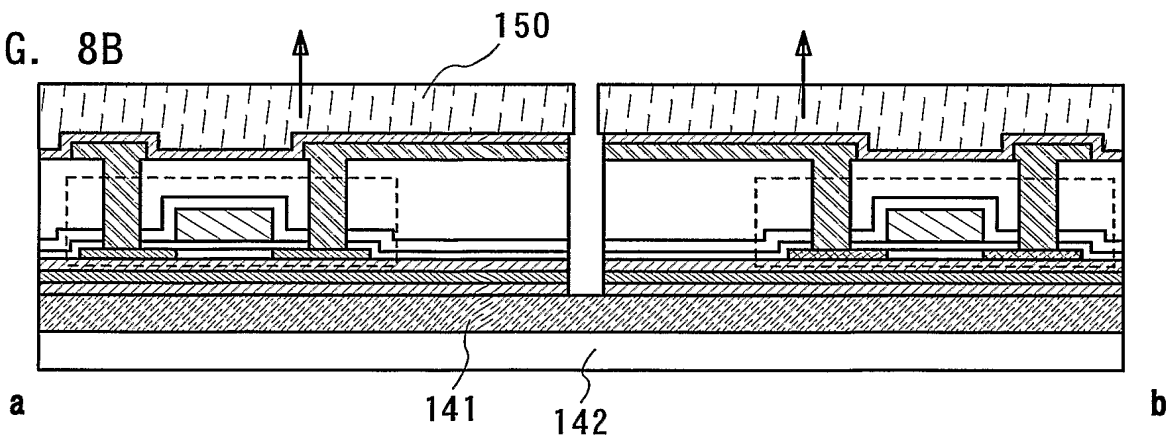
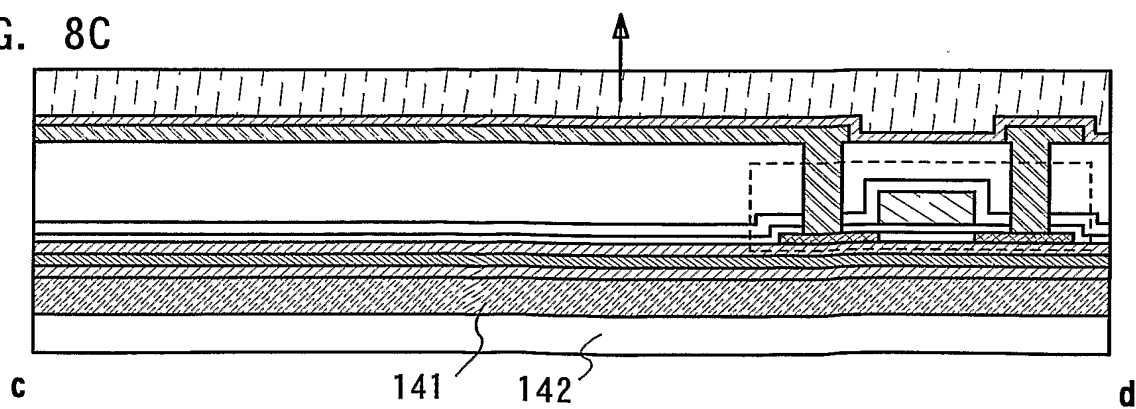


FIG. 8C



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FIG. 9A

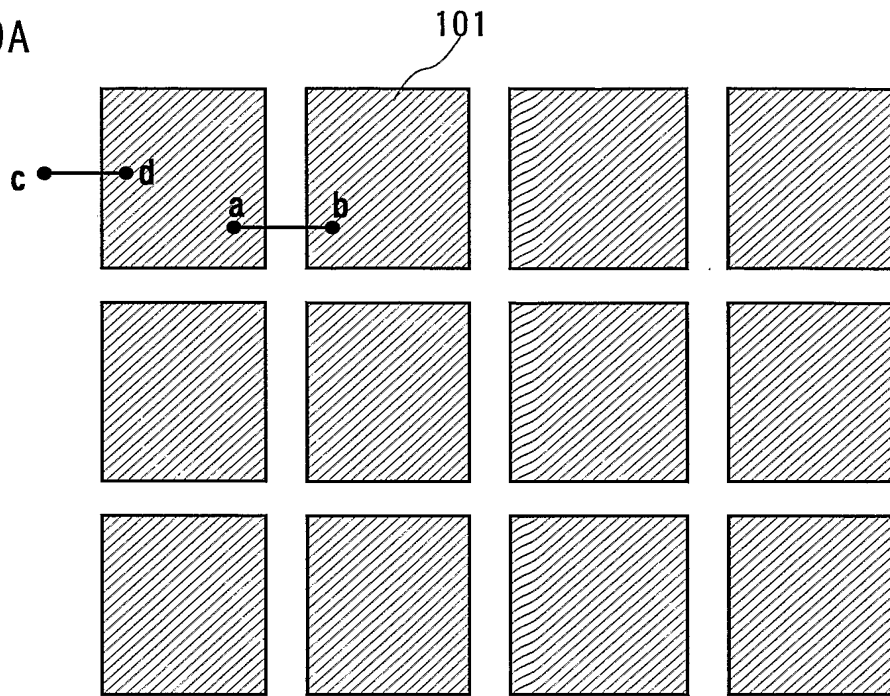


FIG. 9B

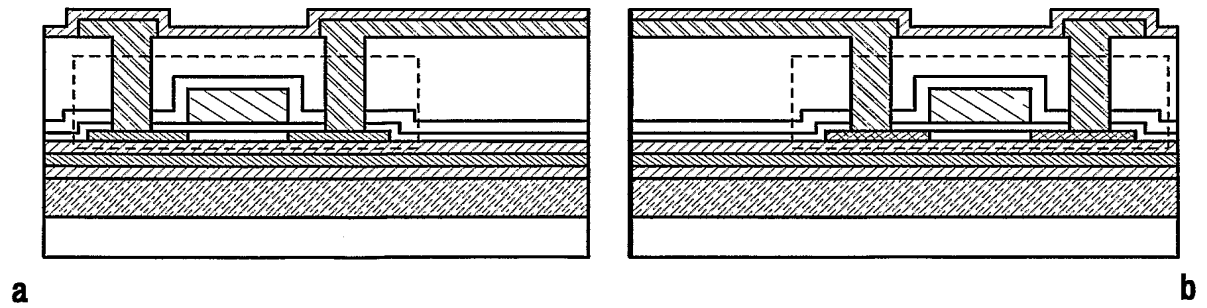
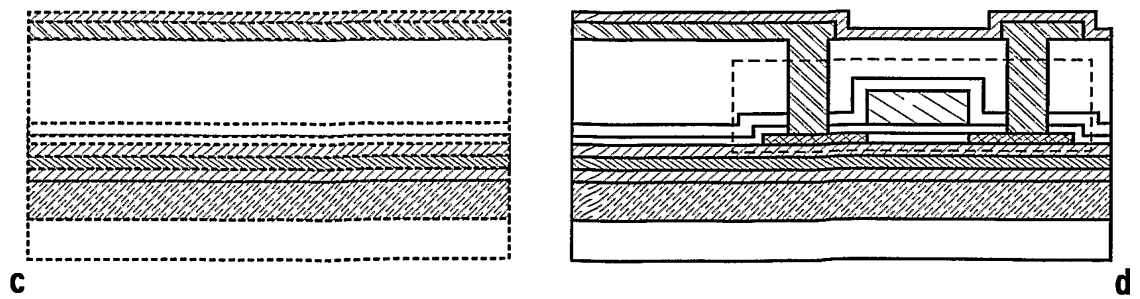
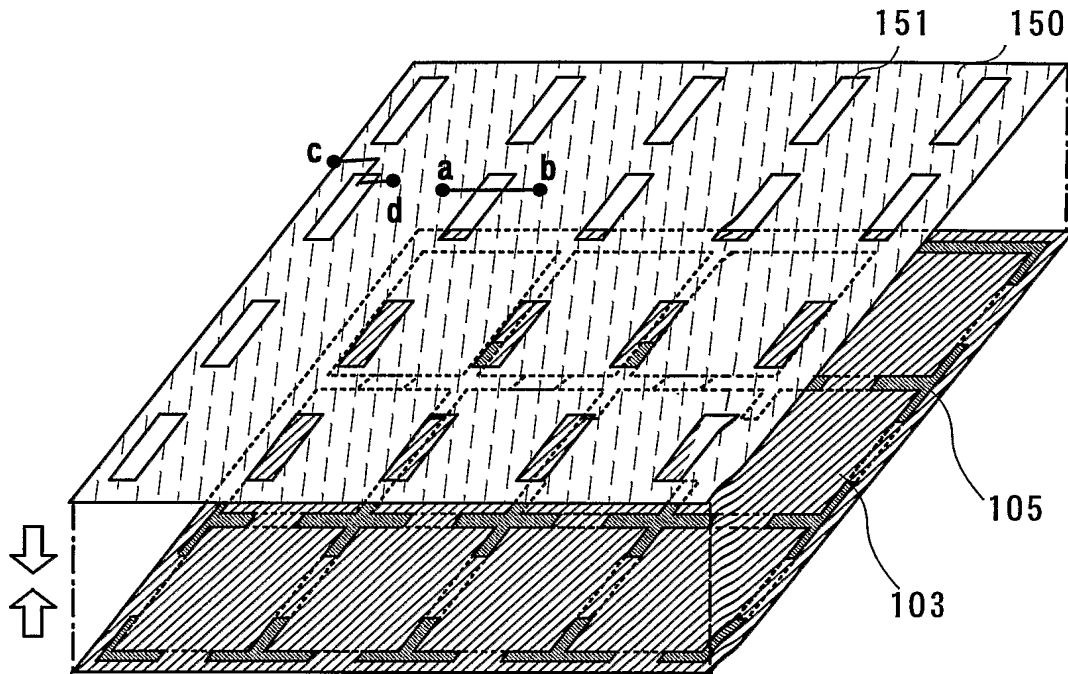


FIG. 9C



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FIG. 10



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FIG. 11A

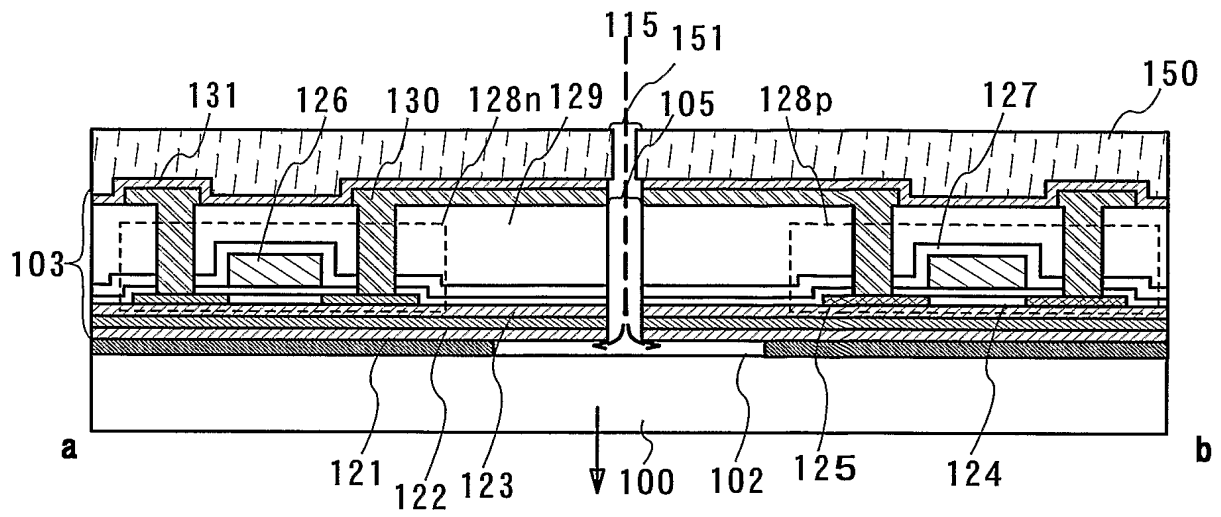
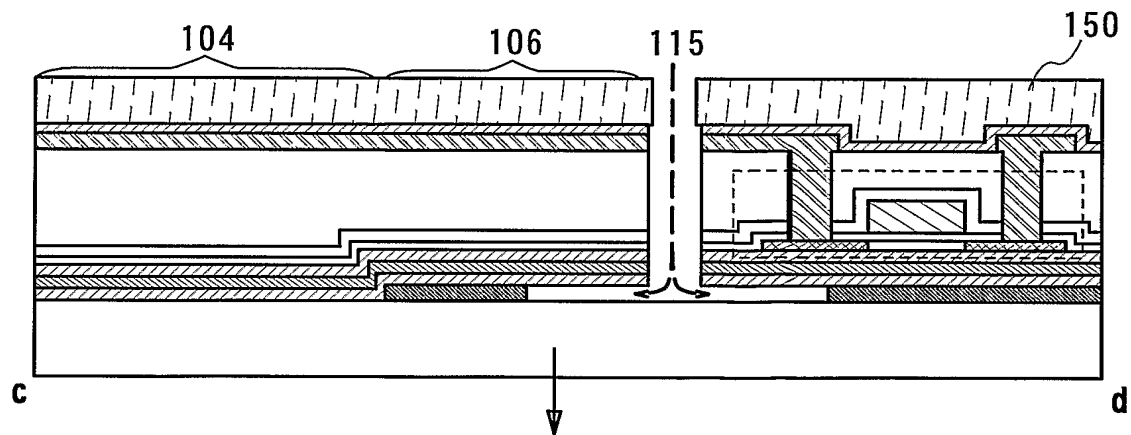


FIG. 11B



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FIG. 12A

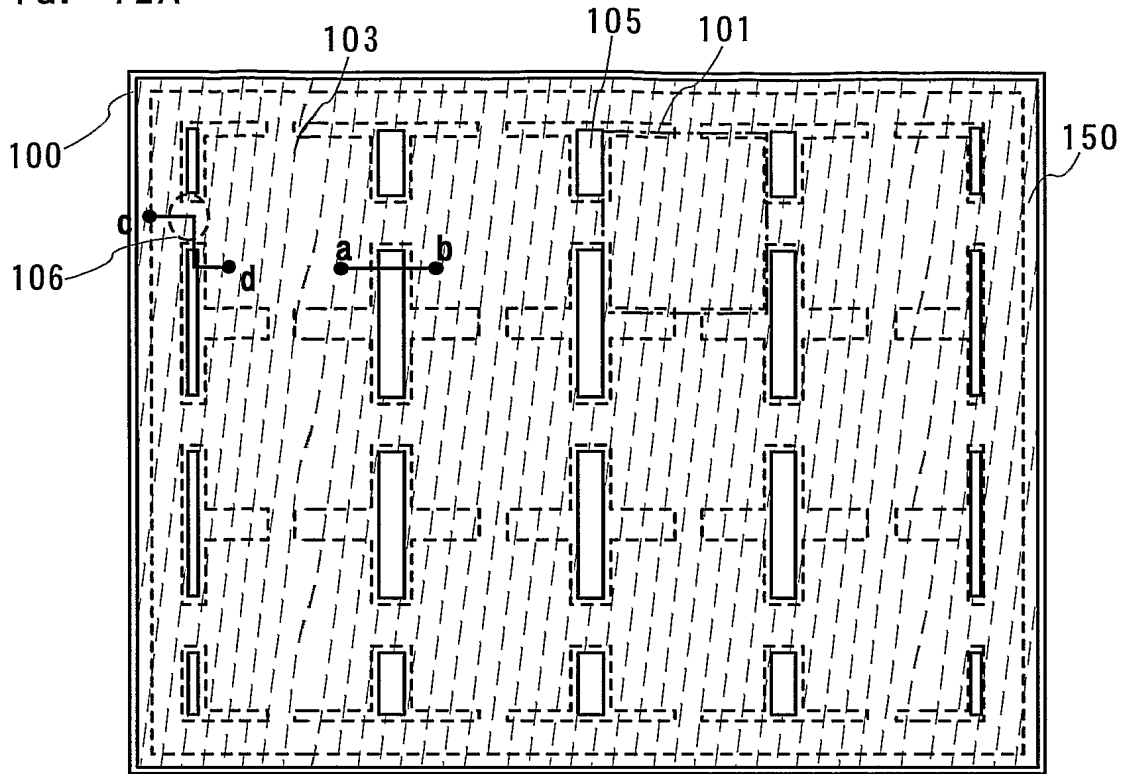


FIG. 12B

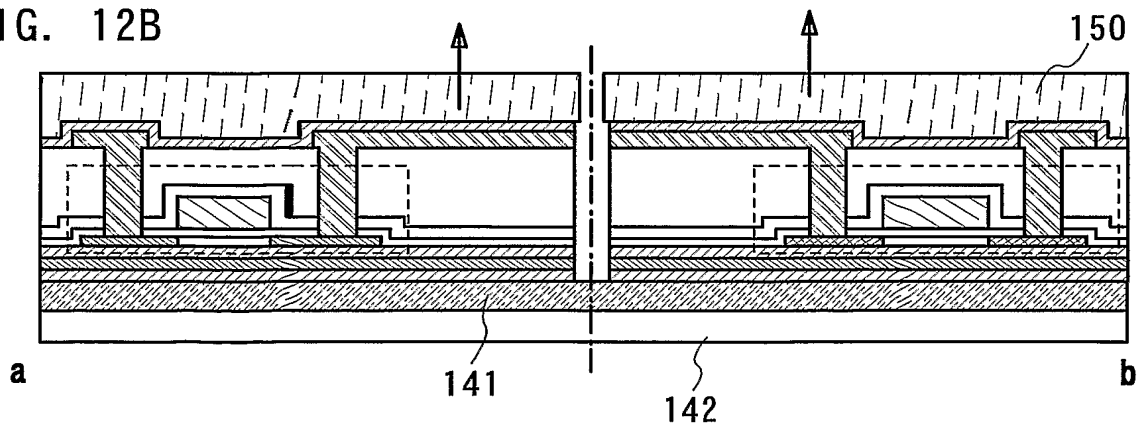
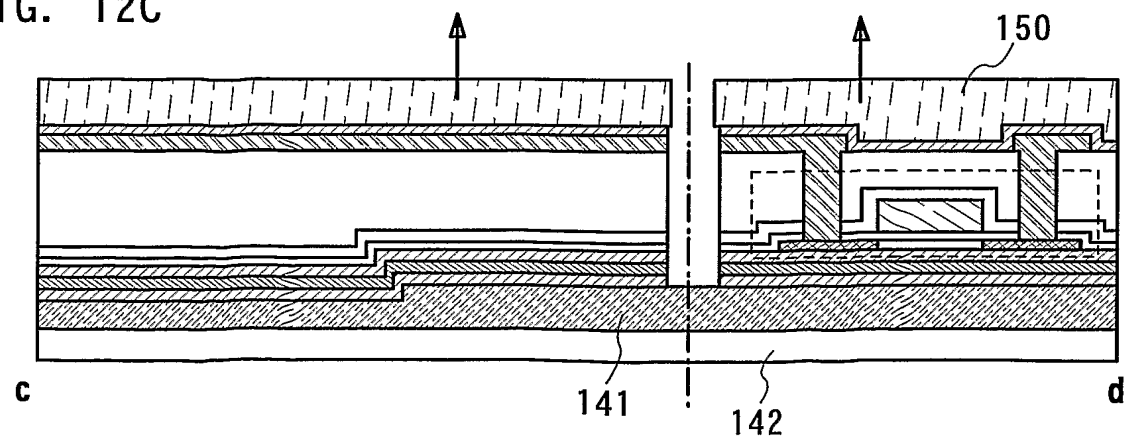
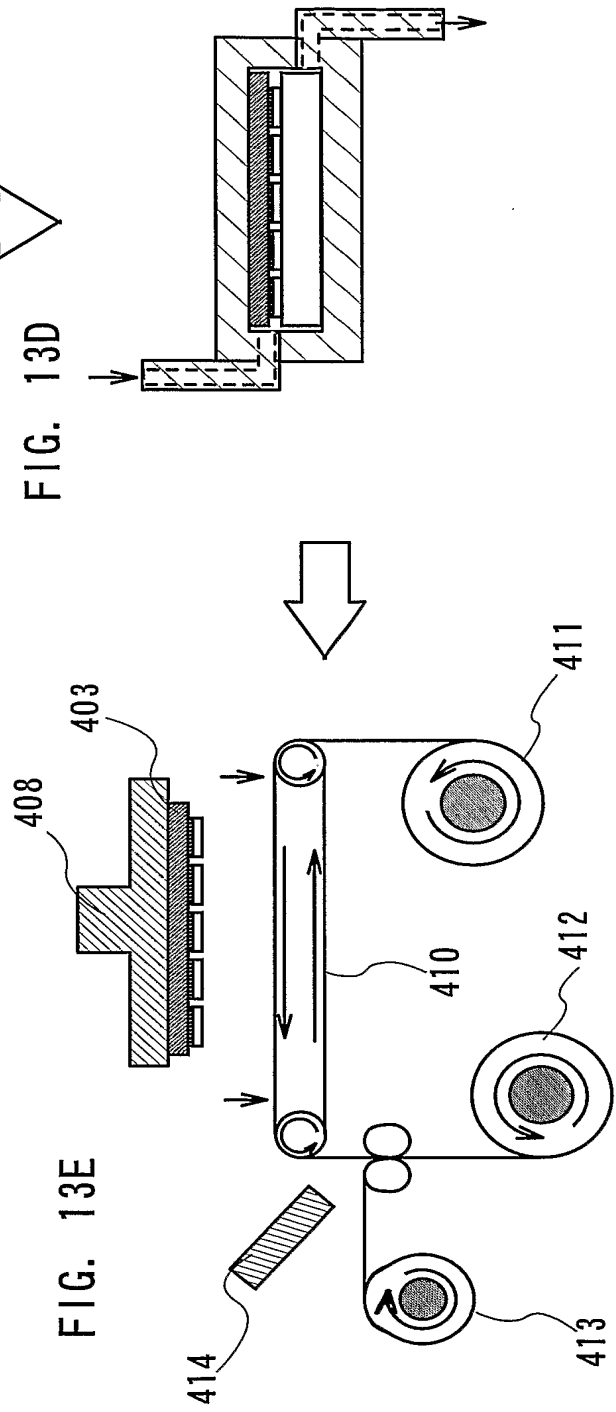
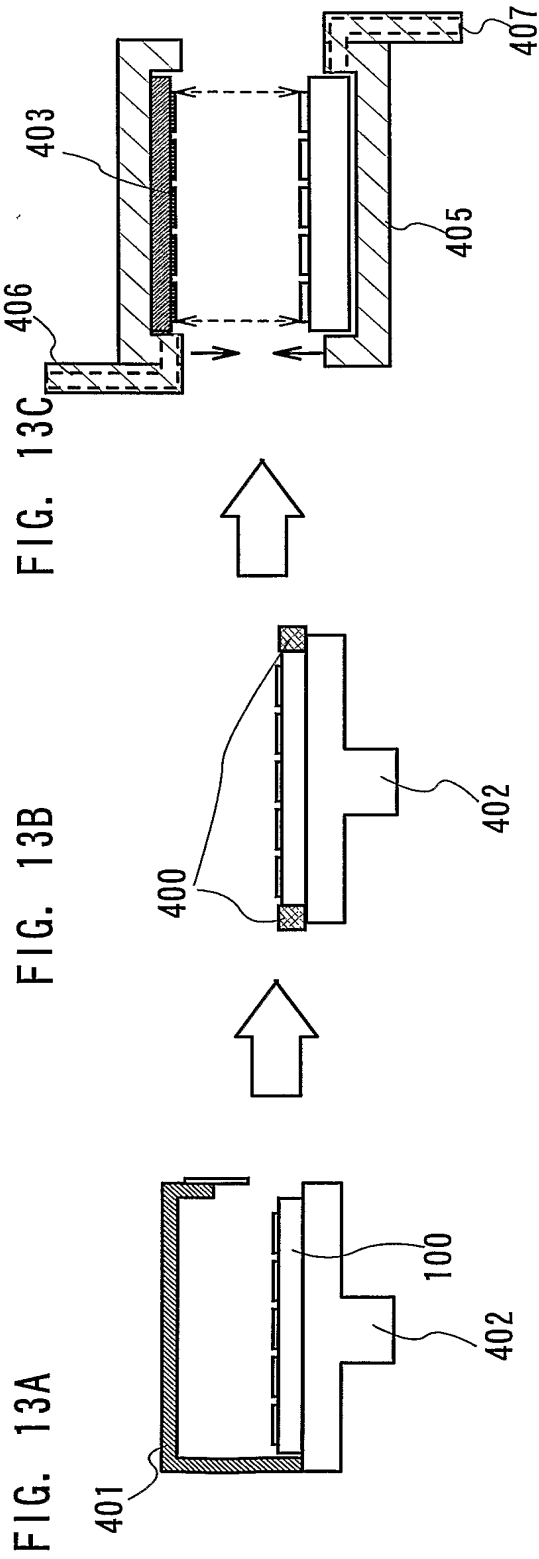


FIG. 12C





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FIG. 14A

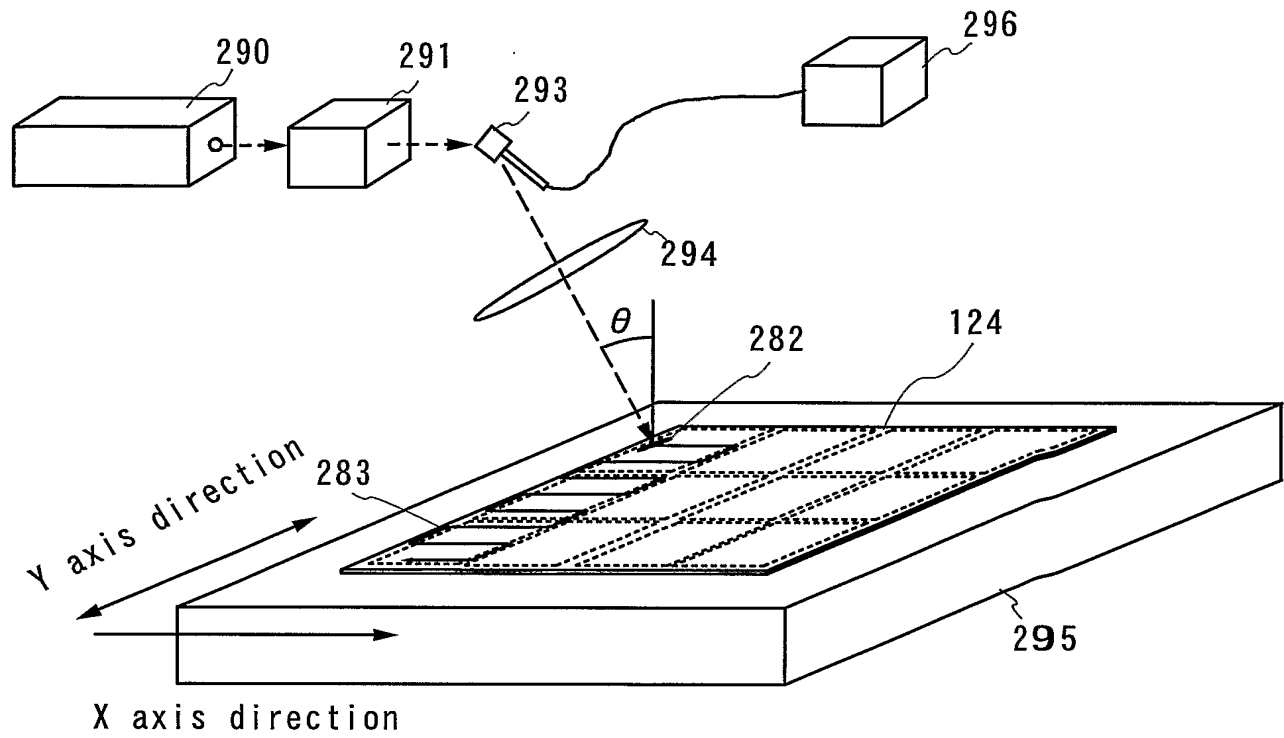
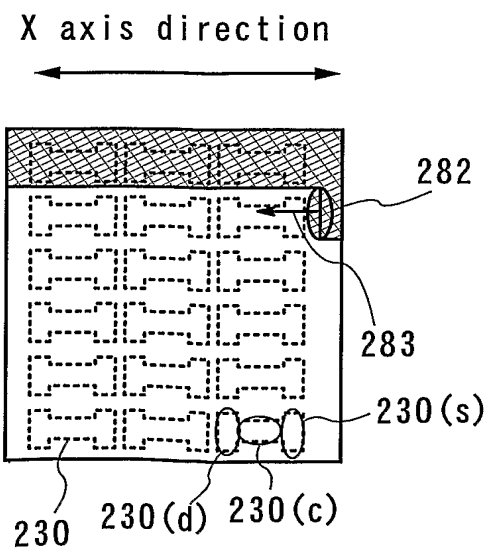
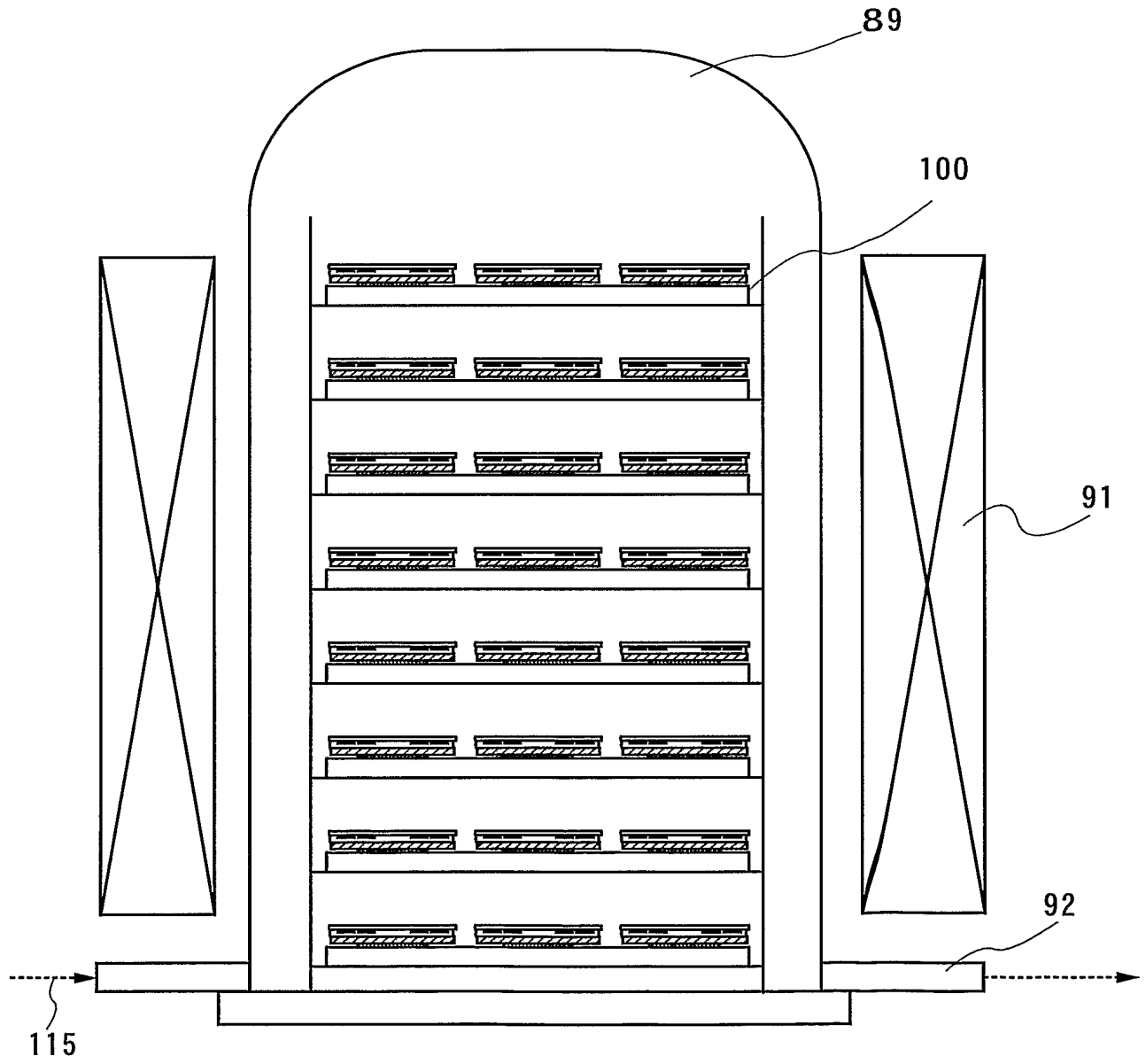


FIG. 14B



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FIG. 15



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FIG. 16A

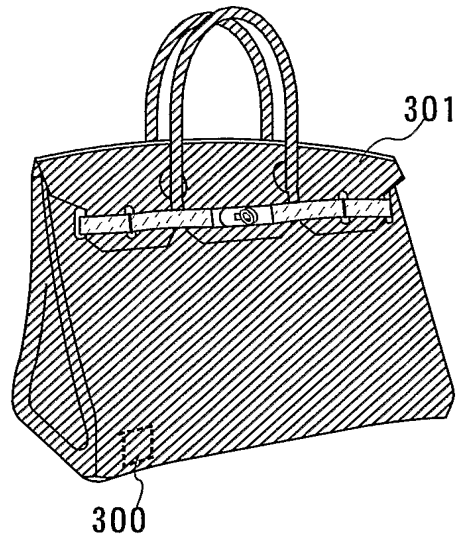
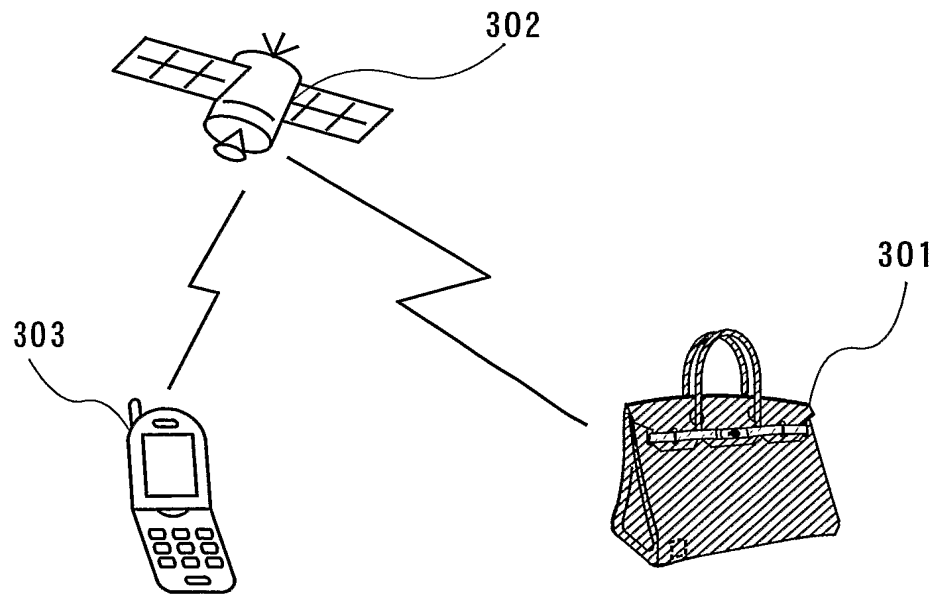


FIG. 16B



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FIG. 17A

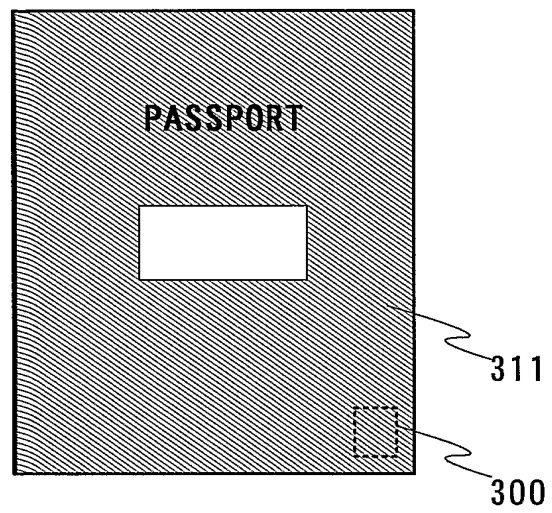
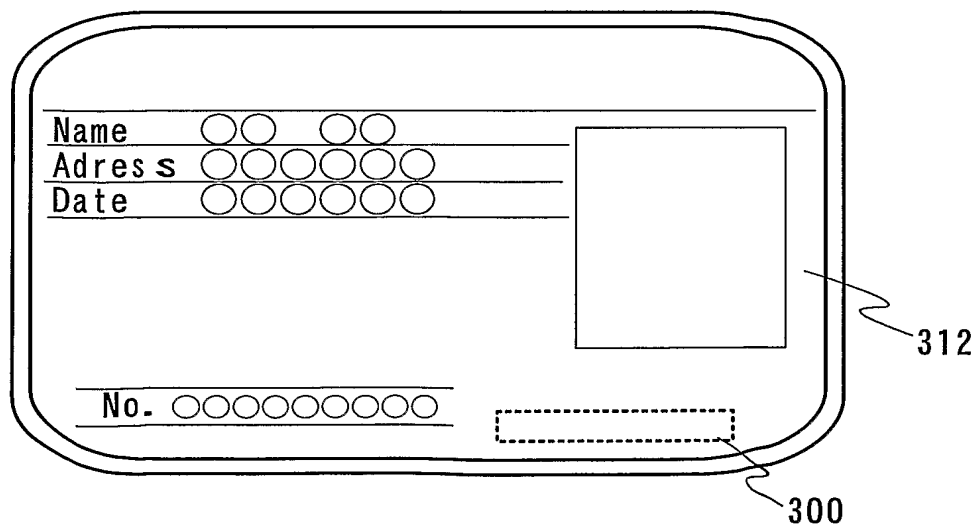
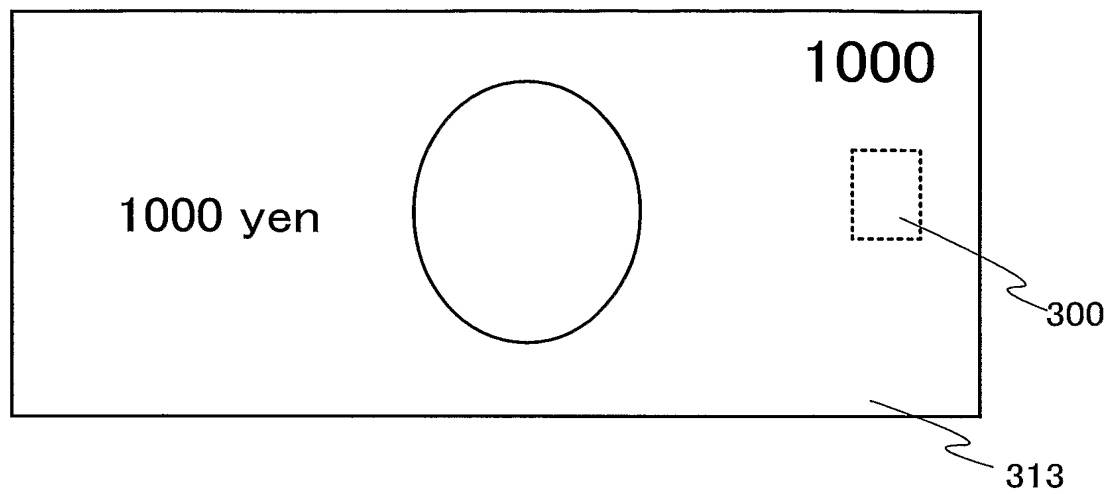


FIG. 17B



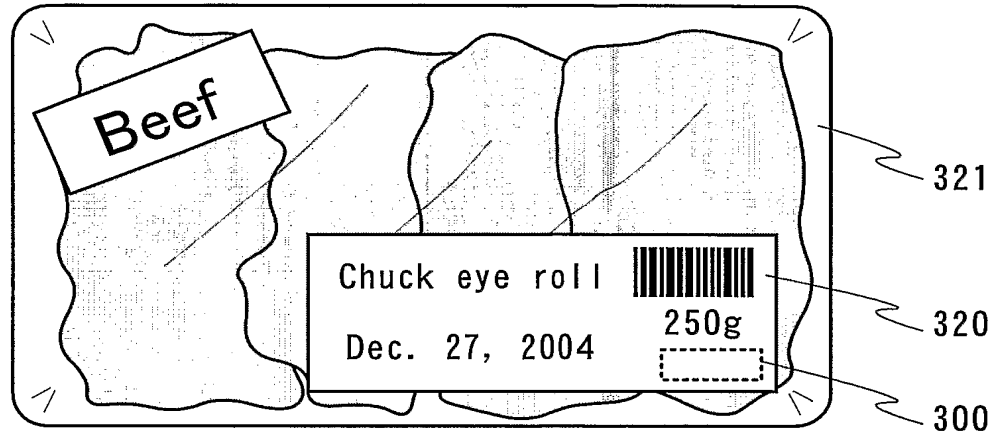
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FIG. 18



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FIG. 19



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FIG. 20A

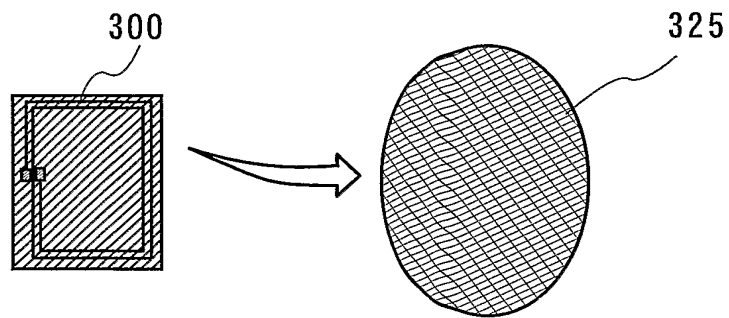
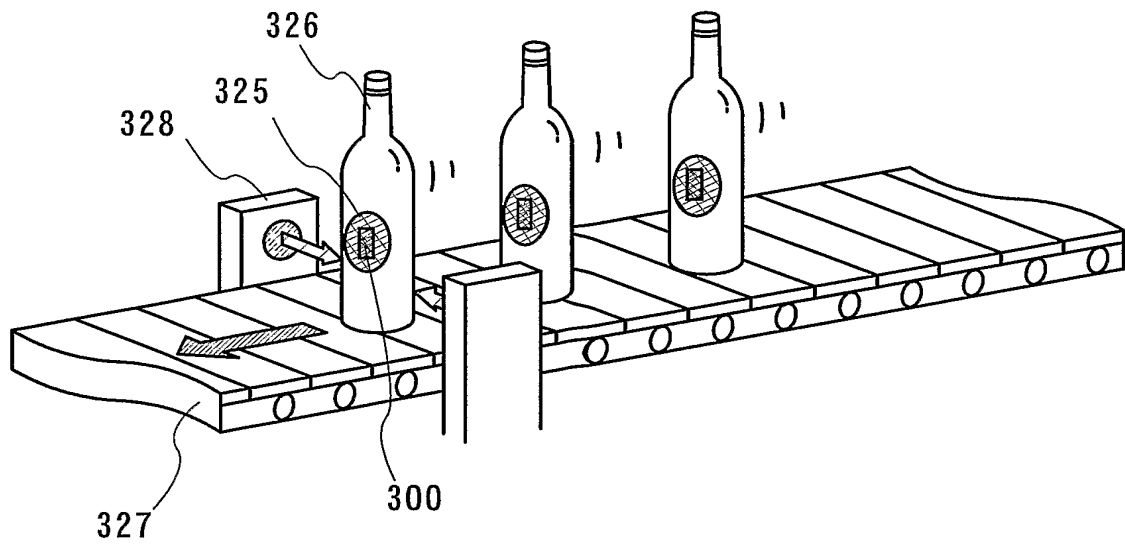
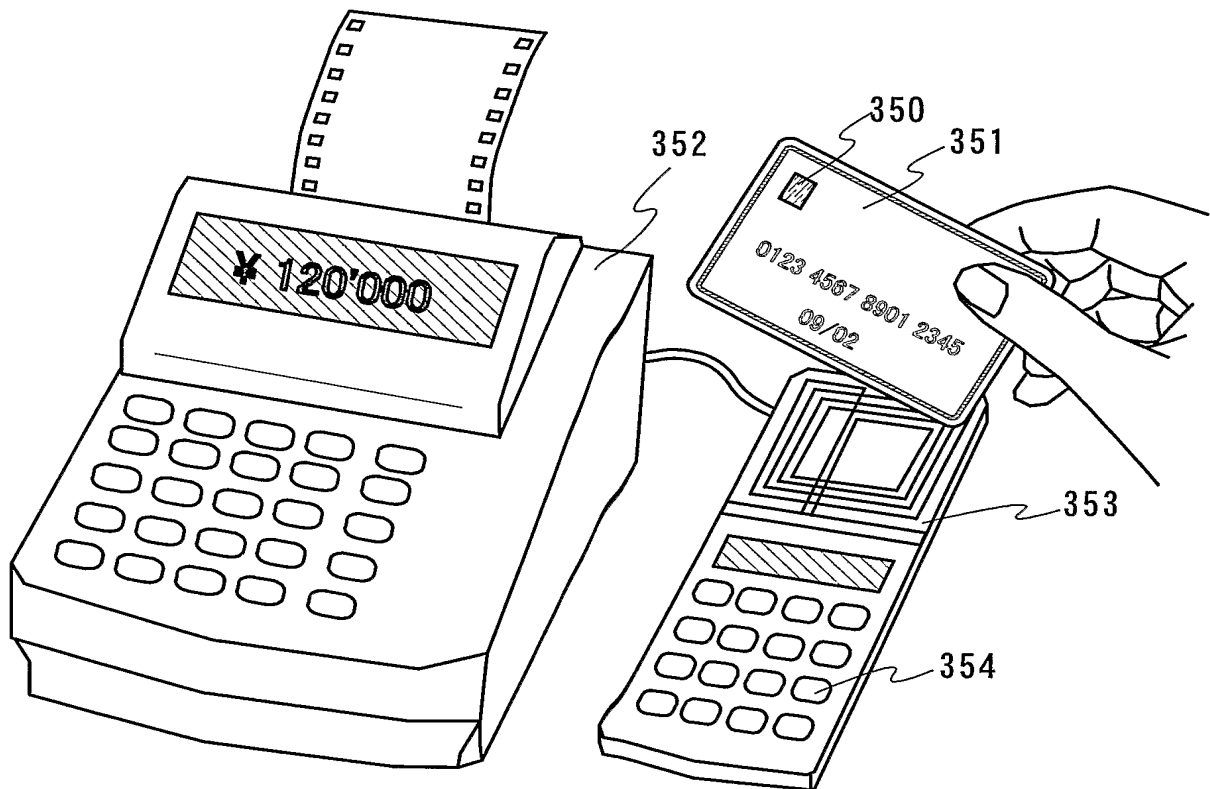


FIG. 20B



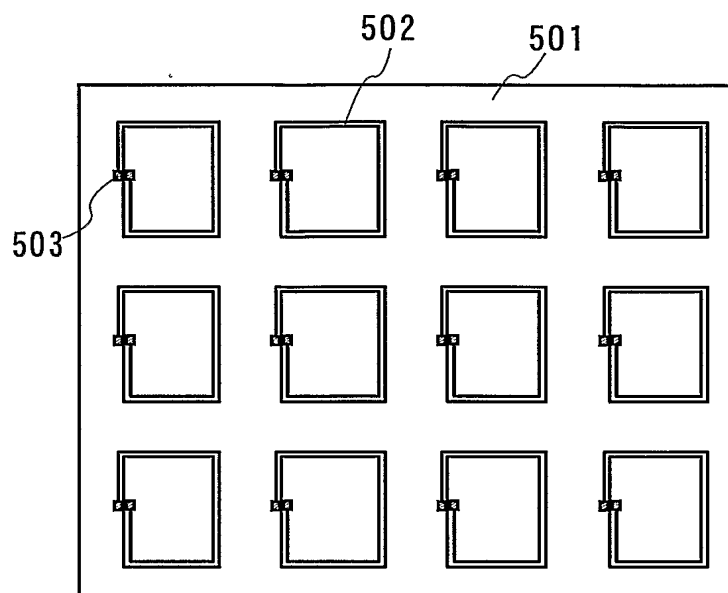
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FIG. 21



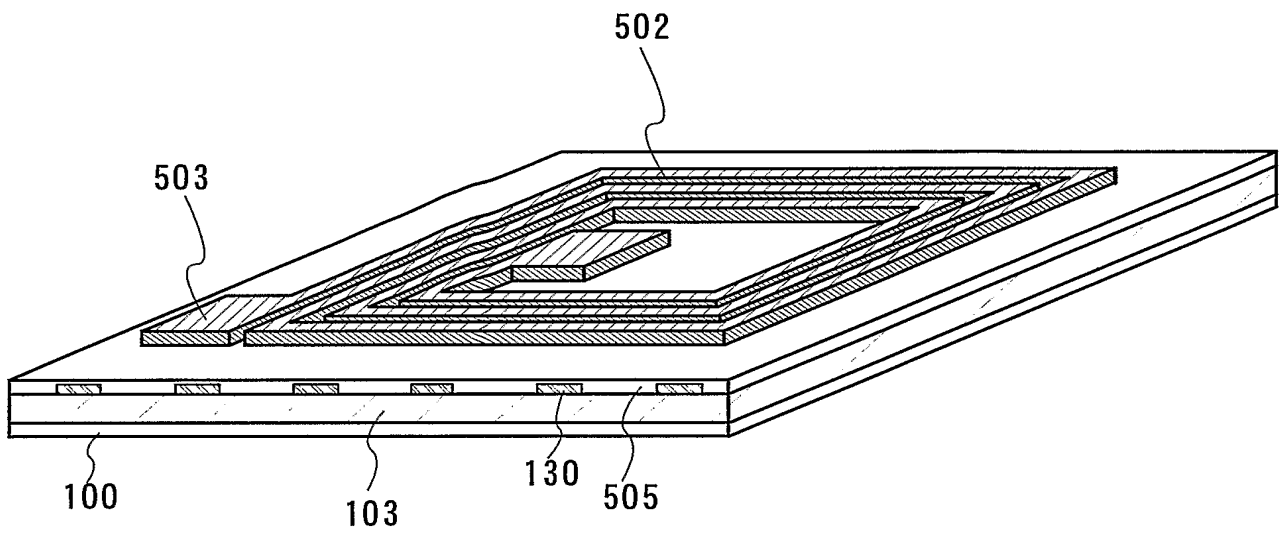
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FIG. 22



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FIG. 23



EXPLANATION OF REFERENCE

89: bell jar, 91: heater, 92: exhaust pipe, 100: insulating substrate, 101: thin film integrated circuit, 102: release layer, 103: TFT layer, 104: region, 105: groove, 106: connecting region, 108: opening portion, 115: etching agent, 121: insulating film, 122: insulating film, 123: insulating film, 124: semiconductor film, 124 (s): source region, 124(c): channel formation region, 124 (d): drain region, 127: interlayer insulating film, 129: interlayer insulating film, 130: wiring, 131: insulating film, 140: means, 141 adhesive, 142: another substrate, 150: means, 151: opening portion, 201: carrier, 202, elevator, 203: belt conveyor, 204: transportation roll, 205: roll, 206: carrier, 207: elevator, 209: operating evaluation device, 210: roll, 211: alignment device, 212: roll, 281: moving direction, 282: laser spot, 283: path, 290: laser oscillator, 291: optical system, 294: galvano mirror, 295: XY stage, 296: device (control device), 300: non-contact IDF chip, 300: IDF chip, 301: non-contact IDF chip mounting bag, 302: satellite, 303: cellular phone, 311: passport, 312: driver's license, 313: paper money, 320: label, 321: pack, 325: label, 326: beer bottle, 327: belt conveyor, 328: writer, 350: temperature, 350: contact IDF chip, 350: contact IDF chip, 351: credit card, 352: register, 353: reader/writer, 354: key, 400: substrate moving arm, 401: carrier, 402: elevator, 403: jig, 405: etching agent introducing chamber, 406: etching agent inlet, 407: etching agent outlet, 408: jig carrying arm, 410: belt conveyor, 411: roll, 412: roll, 413: roll, 414: alignment device, 501: antenna substrate, 502: antenna, 503: connecting terminal, 505: insulating film, 128n: thin film transistor, 128n: n-channel thin film transistor, 128p: p-channel thin film transistor, 208a: roller, and 208b: roller.